

The End of Moore's Law? High Performance ICs Through Modular Chip Design

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Moore's Law

We are coming to the end of transistor shrinking phase





Moore's Law

- Doubling the number of transistors per chip at a constant cost
- Increasingly difficult to maintain this exponential improvement

* Image Source IEEE Spectrum.com

...modular chip design will enable the next phase of Moore's Law

The Next Phase of Moore's Law



- 2.5 and 3D materials
 Reduced complexity of chipto-chip communications
- Specialized System in Packages (SiP)
- Leading semiconductor companies are already moving to heterogeneous 2.5D solutions



After transistor shrinking phase – heterogeneous solutions phase (last page of Moore's Law)

The Value of Modular Chip Design



Chip-scale Open Architecture Allows:

- Increased investment in application- specific chiplets
- Rapid integration for applicationspecific solutions
 - Artificial Intelligence
 - Machine Learning
 - Integrated Security Solutions
 - Direct to Digital Convergence
- Enables low volume / high mix solutions as well as computing at the edge
 - Autonomous systems
 - Small satellites
 - IoT

New Modular Library Enables Rapid Customization

Open systems at chip scale allows unprecedented configurability and flexibility



What is needed next – open architecture at the chip level

How Mercury is Approaching Challenge For Defense Industry?





Accelerating the delivery of advanced trusted computing for defense



Thank you!

Questions?

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